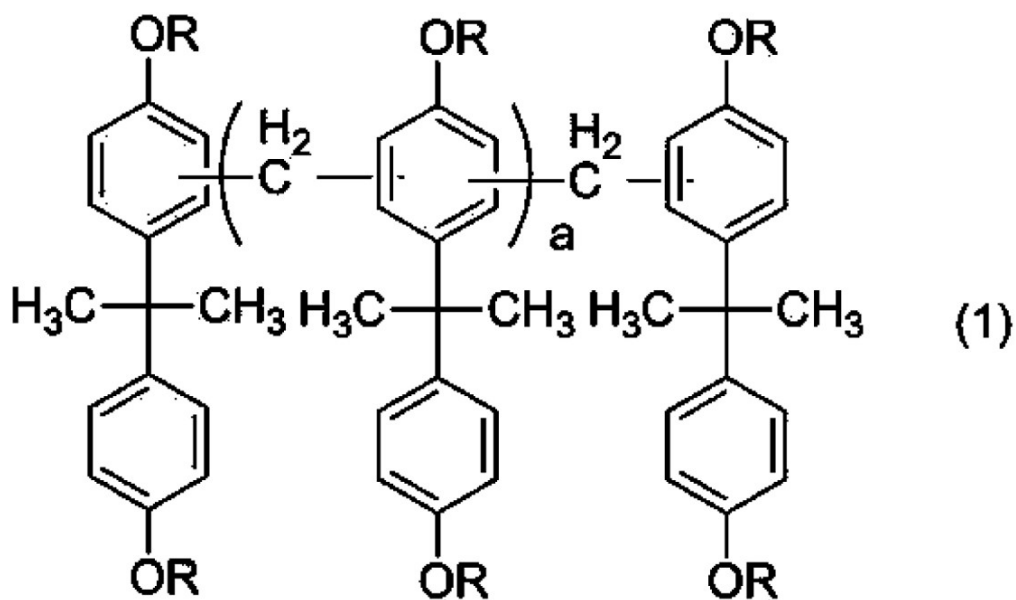


ABSTRACT

PHOTOSENSITIVE RESIN COMPOSITION AND CURED PRODUCT OF SAME

The present invention is a negative photosensitive resin composition which contains (A) an epoxy resin, (B) a compound that has a phenolic hydroxyl group and (C) a cationic photopolymerization initiator. This negative photosensitive resin composition is configured such that: 30% by mass or more of the epoxy resin (A) is an epoxy resin (A-1) that is represented by formula (1) (wherein each R moiety independently represents a glycidyl group or a hydrogen atom, and at least two R moieties among the plurality of R moieties are glycidyl groups; and a represents the average of the number of repeating units, which is a real number within the range of from 0 to 30); and the compound (B) that has a phenolic hydroxyl group and the cationic photopolymerization initiator (C) have specific structures.



[No figure]